

ADHESION PROMOTION OF METAL TO A DIELECTRIC

ABSTRACT

An adhesion solution containing curable amine compounds and curable epoxy compounds are applied to a dielectric material followed by drying the solution and electrolessly plating a thin metal layer on the dielectric material. The composite is then annealed to cure the amine and epoxy compounds. The adhesion solution contains an excess amount of curable amine to curable epoxy. The adhesion solution and method may be used in the manufacture of printed circuit boards.

NO SUITABLE FIGURE